



## Material declaration form

General Information							
IPC	1752	Version	2				
Form type*	Distribute	Version	2				
Sectionals*	Material information	Subsectionals*	A-D				
	Manufacturing information	*: Required Field					

Supplier Information							
Company name*	STMicroelectronics	Response Date*	2025-04-07				
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section				
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section				
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion				
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section				
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html						

## Uncertainty statement

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## Legal statement Supplier acceptance\* true Legal declaration\* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

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Product								
Mfr item number	Mfr item number Mfr item name		Manufacturing site	date				
STM32F098VCT6	921L*442CCC1	A	0959	2025-04-07				
	Amount 675		Unit type	ST ECOPACK grade				
			Each	ECOPACK® 2				

Manufacturing information								
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles						
3	260	3						
Bulk solder termination	Terminal plating	Terminal base alloy	Comment					
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0					
Package designator	Package size	Number of instances	Shape					
QFP	14x14	100	Gull wing					
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901							

QueryList: RoHS Directive 2011/65/EU	Response				
1 - Product(s) meets EU RoHS requireme	true				
2 - Product(s) meets EU RoHS requireme apply)	false				
3 - Product(s) meets EU RoHS requireme	false				
4 - Product(s) does not meet EU RoHS re	false				
Exemption Id.	Description	·			
,					

QueryList : REACH-21st January 2025	Response			
	Response			
1 - Product(s) does not contain REACH S	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg) Application		ppm in product
,	#N/A			

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Material Composition Declaration: note: Substance present with less 0.001mg_will not be declared in this document					Mfr Item Name	921L*442CCC1	675.4487		6000000.0	1000000.0	
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	19.999	mg	supplier	die	Silicon (Si)	7440-21-3	19.253	mg	962712	28504.00
				supplier	metallization	Aluminium (AI)	7429-90-5	0.036	mg	1809	53.56
				supplier	metallization	Copper (Cu)	7440-50-8	0.315	mg	15768	466.86
				supplier	metallization	Cobalt (Co)	7440-48-4	0.001	mg	65	1.92
				supplier	metallization	Tantalum (Ta)	7440-25-7	0.102	mg	5105	151.15
				supplier	metallization	Titanium (Ti)	7440-32-6	0.004	mg	194	5.74
				supplier	metallization	Tungsten (W)	7440-33-7	0.003	mg	129	3.82
				supplier	Passivation	Silicon Nitride	12033-89-5	0.080	mg	4007	118.64
				supplier	Passivation	Silicon Oxide	7631-86-9	0.204	mg	10211	302.33
LEADFRAME	M-011 Other inorganic materials	159.873	mg	supplier	ALLOY	Copper (Cu)	7440-50-8	147.008	mg	919532.6928	217644.95
				supplier	ALLOY	Iron (Fe)	7439-89-6	3.621	mg	22649.29719	5360.88
				supplier	ALLOY	Iron Phosphide (Fe2P)	1310-43-6	0.045	mg	281.4742815	66.62
				supplier	ALLOY	Zinc (Zn)	7440-66-6	0.181	mg	1132.15211	267.97
				supplier	SPOT	Silver (Ag)	7440-22-4	5.490	mg	34336.79991	8127.21
				supplier	LLT	Polyethylene-terephthalate film	25038-59-9	1.432	mg	8959.438971	2120.62
				supplier	шт	NBR	9003-18-3	0.346	mg	2162.6232	511.87
				supplier	LLT	Phenol Resin	28453-20-5	0.346	mg	2162.6232	511.87
				supplier	шт	2,2'-Bis-[4-(4-maleimidephenoxy)phenyl]prop	ane 79922-55-7	0.346	mg	2162.6232	511.87
				supplier	шт	Polyimide film	Proprietary	1.058	mg	6620.275101	1566.96
DIE ATTACH	M-011 Other inorganic materials	4.080	mg	supplier	GLUE	Silver (Ag)	7440-22-4	3.488	mg	855000	5164.35
	3		,	supplier	GLUE	Dodecyl acrylate	2156-97-0	0.102	mg	25000	151.00
				supplier	GLUE	methylene diacrylate	42594-17-2	0.326	mg	80000	483.21
				supplier	GLUE	Diglycidylphenyl glycidyl ether	13561-08-5	0.082	mg	20000	120.80
				supplier	GLUE	Isobornyl Methacrylate	7534-94-3	0.041	mg	10000	60.40
				SVHC	GLUE	dimethylbenzyl peroxide	80-43-3	0.041	mg	10000	60.40
BONDING WIRE	M-011 Other inorganic materials	1.422	mg	supplier	BONDING WIRE	Silver (Ag)	7440-22-4	1.372	mg	965000	2031.87
_ · · · · ·				supplier	BONDING WIRE	Gold (Au)	7440-57-5	0.007	mg	5000	10.53
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3	0.043	mg	30000	63.17
ENCAPSULATION	M-011 Other inorganic materials	484.618	mg	supplier	MOLDING COMPOUND	Silica, vitreous	60676-86-0	419.550	mg	865733	621142.95
ENCAPSULATION	2.1 Otto norgano maonao	101.010	···y	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary	35.883	mg	74044	53124.82
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary	23.922		49363	35416.78
							· · ·		mg		
				supplier	MOLDING COMPOUND	3-Mercaptopropyl trimethoxysilane	4420-74-0	2.392	mg	4936	3541.46
				supplier	MOLDING COMPOUND	Quartz	14808-60-7	1.435	mg	2962	2125.16
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4	1.435	mg	2962	2125.16
FINISHING	M-011 Other inorganic materials	5.457	mg	supplier	COATING	Tin (Sn)	7440-31-5	5,457	mg	1000000	8079.07

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